



NEW TWIN-CUT DIE-CUTTING SYSTEM BY OMET

PRESS RELEASE

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The patented Twin-Cut by Omet is an innovative die-cutting system that uses two pairs of magnetic cylinders, rotating at constant speed during the cutting phase and accelerating alternately during the rest phase, to allow die-cutting on all formats without the need for laborious cylinder replacement.

Changing format is simply a question of inserting new magnetic dies - a process which can be programmed and synchronised from the control panel. Omet's Twin-Cut eliminates the need for purchasing multiple cylinders, and improves the speed and efficiency of in-line label and folding carton production. Find Omet in booth 3007 at Labelexpo Americas 2004.

Comments Massimo Belligardi, "We're very excited about exhibiting the Twin Cut system at Labelexpo Americas this year. The technology found in the new machine promises to make label and folding carton production a faster and more cost-effective process."

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Notes to Editors

1. Further information regarding Labelexpo Americas 2004 can be found at www.labelexpo-americas.com
2. For further information about Omet, visit www.omet.it
3. Labelexpo Americas is supported by TLMI. Further information about TLMI can be found at www.tlmi.com
4. The Label Industry Global Awards will take place at the Donald E Stephens Convention Centre on Monday 13 September 2004. www.labelwards.com.
The awards are as follows:
 - R. Stanton Avery Lifetime Achievement Award [*sponsored by: Avery Dennison*]
 - Label Industry Award for Continuous Innovation [*sponsored by: Labels & Labeling, Label and Narrow Web, and NarroWebtech*]
 - Label Industry Award for New Innovation [*sponsored by Creo and HP*].
5. Interviews with Roger Pellow, Labelexpo Managing Director, are available on request.
6. Photography of previous Labelexpo events is available upon request.
7. Further Exhibition dates:
 - *Labelexpo Americas 2004*
13-16 September, Donald E Stephens Convention Centre, Chicago, USA
 - *Labelexpo Singapore 2004*
23-25 November, Singapore Expo Centre
 - *India Label Show*
3-6 December 2004, Pragati Maidan, New Delhi, India
 - *Packaging Services 2005*
10-12 May, Donald E Stephens Convention Centre, Chicago, USA
 - *Labelexpo Europe 2005*
21-24 September, Brussels Expo, Belgium
8. Further Conference dates:
 - *Smart Packaging 2004*
8-9 September, Donald E Stephens Convention Centre, Chicago, USA
 - *The European Label Summit 2004*
12-13 October, Prague Marriott Hotel, Czech Republic
 - *PISEC 05*
18-20 April, Vienna, Austria
 - *The Latin American Label Summit 2005*
17-18 May, Sao Paulo, Brazil
9. Labelexpo is organized by Tarsus Group plc, the international media group with interests in exhibitions, conferences, publishing and the Internet. For further information on Tarsus please see www.tarsus-group.com.